

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC050N10NS5	**Issued**	27. April 2022
MA#	MA005729480		
Package	PG-TDSON-8-50	**Weight***	105.72 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.185	1.12	1.12	11212	11212
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		129	
	non noble metal	zinc	7440-66-6	0.055	0.05		516	
	non noble metal	iron	7439-89-6	1.090	1.03		10313	
	non noble metal	copper	7440-50-8	44.271	41.87	42.96	418770	429728
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	403	403
encapsulation	organic material	carbon black	1333-86-4	0.082	0.08		772	
	plastics	epoxy resin	-	6.447	6.10		60986	
	inorganic material	silicondioxide	60676-86-0	34.277	32.42	38.60	324229	385987
leadfinish	non noble metal	tin	7440-31-5	1.264	1.20	1.20	11954	11954
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	274	274
solder	noble metal	silver	7440-22-4	0.041	0.04		388	
	non noble metal	tin	7440-31-5	0.082	0.08		776	
	non noble metal	lead	7439-92-1	1.518	1.44	1.56	14359	15523
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	zinc	7440-66-6	0.018	0.02		174	
	non noble metal	iron	7439-89-6	0.368	0.35		3478	
	non noble metal	copper	7440-50-8	14.930	14.12	14.49	141224	144919
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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